
Design Example Report

Title	<i>0.25 W Non-Isolated Power Supply Without Electrolytic Capacitors Using LinkSwitch™-TNZ LNK3302D</i>
Specification	90 VAC – 132 VAC Input, 5 V, 50 mA Output
Application	Home and Building Automation
Author	Applications Engineering Department
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Summary and Features

- Highly integrated solution with LNK3302D
- No electrolytic capacitors
- Very wide ambient temperature operating range -40 to 70 °C
- Optimized for low audible noise <25 dB
- Low component count with integrated 725 V power MOSFET, current sensing and protection
- <120 μ A standby input current across AC line
- Zero-crossing signal output synchronized to AC line
- Meets EN550022 conducted EMI
- Compact solution 1" x 1.20", 11 mm maximum height
- Load short-circuit protection

PATENT INFORMATION

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Power Integrations

5245 Hellyer Avenue, San Jose, CA 95138 USA.
Tel: +1 408 414 9200 Fax: +1 408 414 9201
www.power.com

Table of Contents

1	Introduction.....	4
2	Power Supply Specification.....	5
3	Schematic.....	6
4	Circuit Description	7
4.1	Input Rectifier and Filter	7
4.2	Input Protection	7
4.3	Power Factor Circuit.....	7
4.4	LNK3302 Power Supply Operation	7
4.5	Feedback and Output Voltage Regulation	8
4.6	Zero-Crossing Detection	8
5	PCB Layout.....	9
6	Bill of Materials	10
6.1	Electrical Parts.....	10
6.2	Optional Part.....	10
6.3	Mechanical Parts.....	10
7	Design Spreadsheet.....	11
8	Performance Data	13
8.1	Efficiency	13
8.2	No-Load Input Current.....	14
8.3	Line Regulation at Different Ambient Temperatures.....	15
8.3.1	Line Regulation Performance at Room Ambient Temperature.....	15
8.3.2	Line Regulation Performance at 70°C Ambient Temperature.....	16
8.3.3	Line Regulation Performance at -40°C Ambient Temperature.....	17
8.4	Load Regulation	18
9	Waveforms.....	19
9.1	Zero-Crossing Detection	19
9.1.1	Zero-Crossing Detection at Normal Operation	19
9.1.1.1	100% Load	19
9.1.1.2	0% Load.....	20
9.1.2	Zero-Crossing Detection at Start-up.....	21
9.1.2.1	0° Start-up Phase.....	21
9.1.2.2	90° Start-up Phase	22
9.1.3	Zero Crossing Detection Delay.....	24
9.2	Output Voltage at Start-up	25
9.3	Switching Waveforms.....	26
9.3.1	Primary MOSFET Drain-Source Voltage and Current at Normal Operation. 26	
9.3.1.1	100% Load	26
9.3.1.2	0% Load.....	27
9.3.2	Primary MOSFET Drain-Source Voltage and Current at Start-up Operation 28	
9.3.2.1	100% Load	28
9.3.2.2	0% Load.....	29
10	Thermal Performance.....	30
10.1	Test Set-up	30



10.1.1	Thermal Performance (50 °C Ambient Temperature).....	30
10.1.2	Thermal Performance (-40 °C Ambient Temperature)	31
10.1.3	Thermal Performance (70 °C Ambient Temperature).....	31
10.1.4	Thermal Performance (Room Ambient Temperature)	31
11	Conducted EMI	32
11.1	Test Set-up	32
11.2	Equipment and Load Used	32
11.3	Conducted EMI Test Results	33
12	Line Surge.....	34
12.1	Differential Surge Test Results.....	34
12.2	Ring Wave Surge Test Results	34
13	Audible Noise	35
13.1	Audible Noise Test Set-up	35
13.2	Audible Noise Measurements	36
13.2.1	Audible Noise Scan.....	36
14	Revision History	37

Important Note: Although this board is designed to satisfy safety isolation requirements, the engineering prototype has not been agency approved. Therefore, all testing should be performed using an isolation transformer to provide the AC input to the prototype board.



1 Introduction

This engineering report describes a high-side buck converter designed to provide a nominal output voltage of 5 V at 50 mA load from a low-line input voltage range of 90 VAC to 132 VAC, as well as a zero-crossing detection (ZCD) signal. This power supply utilizes the LNK3302D from the LinkSwitch-TNZ family of ICs.

This document contains the complete power supply specifications, bill of materials, circuit schematic and printed circuit board layout, along with performance data and electrical waveforms.

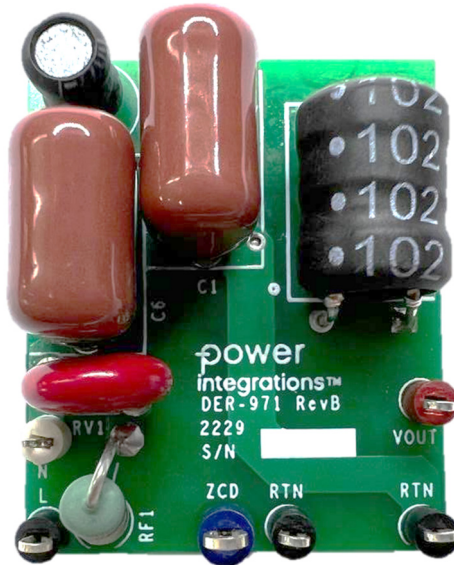


Figure 1 – Populated Circuit Board, Top View.

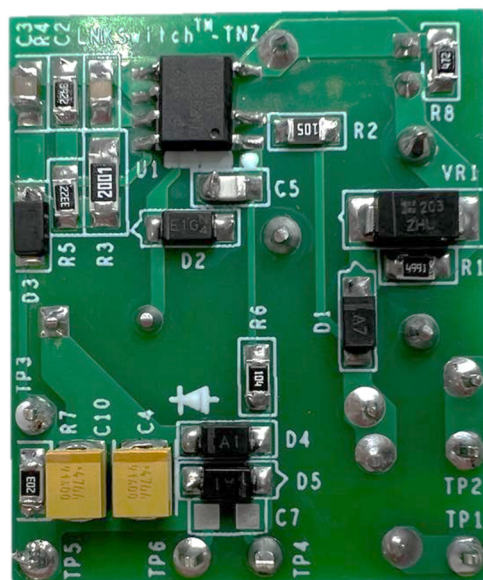


Figure 2 – Populated Circuit Board, Bottom View.

2 Power Supply Specification

The table below represents the minimum acceptable performance of the design. Actual performance is listed in the results section.

Description	Symbol	Min	Typ	Max	Units	Comment
Input						
Voltage	V_{IN}	90		132	VAC	2 Wire – no P.E.
Frequency	f_{LINE}	47	50/60	64	Hz	
No-load Input Current			113		μA	115 VAC.
Output						
Output Voltage	V_{OUT}		5		V	$\pm 5\%$.
Output Current	I_{OUT}		0.05		A	
Total Output Power						
Continuous Output Power	P_{OUT}		0.25		W	
Efficiency						
Full Load	η	66			%	Measured at P_{OUT} 25 °C.
Environmental						
Conducted EMI		Meets CISPR22B / EN55022B				
Safety		Designed to meet IEC 60950-1				
Surge			1		kV	1.2/50 μs surge, IEC 1000-4-5, Series Impedance: Surge: 2 Ω
Ring Wave			2.5		kV	Ring Wave: 12 Ω

3 Schematic

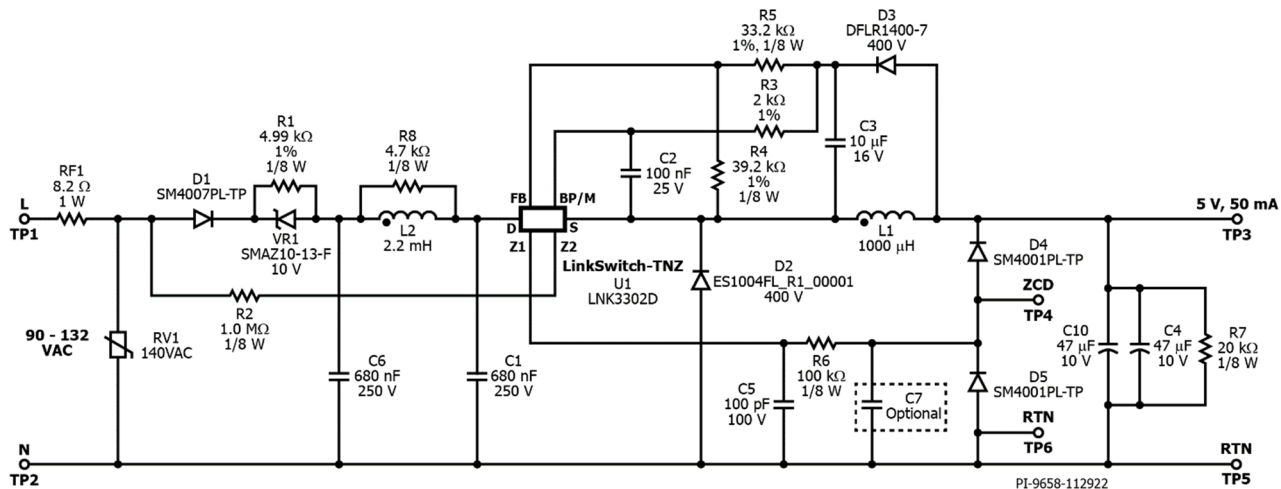


Figure 3 – Schematic.

4 Circuit Description

This circuit is configured as a high-side buck topology power supply utilizing the LNK3302D.

4.1 Input Rectifier and Filter

The AC input voltage is half-wave rectified by a single diode D1. To correctly measure the zero-crossing signal, a single diode connection is recommended over putting the additional diode on the neutral line.

The rectified DC is then filtered by the bulk storage capacitors C1 and C6. For outdoor applications where operating temperatures are higher, a replacement for C1 and C6 is suggested in the bill of materials section under optional parts. Inductor L2, C1 and C6 form an input pi filter, which attenuates differential mode conducted EMI. The damping resistor R8 reduces the Q factor of the inductor L2 to allow noise filtering more effective at wider bandwidth.

4.2 Input Protection

The fusible resistor RF1 provides safety protection against catastrophic circuit failures. It also reduces inrush current at start-up. Varistor RV1 protects against surge events.

4.3 Power Factor Circuit

Power Integrations' RZ circuit, that is resistor R1 and Zener diode VR1, minimizes the no-load input current that is important in many 2-wire switch or dimmer applications. Zener diode VR1 is rated 1 W with a 10 V clamping voltage. Higher Zener voltage may reduce no-load input current further, but it might cause higher power dissipation during surge. Resistor R1 is tuned either at no-load or at standby, whichever is applicable. The resistance is set such as its peak voltage is just below the Zener voltage. This yields the lowest input current.

4.4 LNK3302D Power Supply Operation

The LinkSwitch-TNZ IC combines a high-voltage power MOSFET switch, a power supply controller, and a Zero Crossing Detector in a single device. Unlike conventional PWM (pulse width modulator) controllers, the LinkSwitch-TNZ IC uses a simple ON/OFF control to regulate the output voltage. The LinkSwitch-TNZ controller consists of an oscillator, feedback (sense and logic) circuit, 5 V regulator, BYPASS pin undervoltage circuit, over-temperature protection, line and output overvoltage protection, frequency jittering, current limit circuit, leading edge blanking and a 725 V power MOSFET.

This design is configured as a high-side buck converter using U1 LNK3302D. At AC start-up, the device starts switching once the BYPASS (BP/M) pin voltage charges to V_{BP} . A 100 nF capacitor C2 connected to BP sets the current limit to standard.

When the power MOSFET turns ON, current flows to the load via inductor L1. Energy is stored in the inductor, and the output capacitors C4 and C10 gets charged. When the



MOSFET turns OFF, the stored energy from L1 is released to the load via free-wheeling diode D2. The charge stored in C4 and C10 supplies the current until the next switching event occurs. An internal current source attached to the DRAIN (D) pin charges C2 to provide power to the IC's controller. Once the output voltage has been set, the device controller will be powered from the output via a feedback diode D3 and a current-limiting resistor R3 to reduce losses.

4.5 Feedback and Output Voltage Regulation

In this high-side buck, direct feedback configuration, the rectified voltage across L1 via D3 and C3 tracks the output voltage. Resistors R3 and R4 divides the voltage such that the FB pin is set to 2 V. When the current delivered into this pin exceeds I_{FB} (49 μ A), a low logic level (disable) is generated at the output of the feedback circuit. This output is sampled at the beginning of each cycle on the rising edge of the clock signal. If high, the power MOSFET is turned on for that cycle (enabled), otherwise the power MOSFET remains off (disabled). The current limit circuit senses the current in the power MOSFET. When this current exceeds the internal threshold (I_{LIMIT}), the power MOSFET is turned off for the remainder of that cycle.

Regulation is maintained by skipping switching cycles. As the output voltage rises, the current into the FEEDBACK pin will rise. If this exceeds I_{FB} then subsequent cycles will be skipped until the current reduces below I_{FB} . Thus, as the output load is reduced, more cycles will be skipped and if the load increases, fewer cycles are skipped.

A small pre-load R7 is required to limit the output voltage to about 110% of the rated voltage during light load or no-load condition.

4.6 Zero-Crossing Detection

The Z1 and Z2 pins are configured to provide a loss-less (<5 mW) zero-crossing detection (ZCD) circuit. Z2 is connected to one of the input AC lines through resistor R2 while Z1 forms the ZCD signal output.

When the AC voltage is more positive with respect to Neutral, D4 is forward-biased and clamps ZCD output to $V_{OUT} + 0.7$ V. At the negative-going phase of the AC input, D5 is forward-biased and clamps ZCD output to -0.7 V.

The passive components comprised of R2, C5, R6, and optional C7 provide noise filtering to ensure clean ZCD signal. C7 is a placeholder for the additional filter if needed. Diode D5 has capacitance that helps avoid adding the extra capacitor. However, too much capacitance will cause more delay.



5 PCB Layout

Number of layers:	2
PCB Board thickness:	1.59 mm / 0.062 inches
Material:	FR4
Copper thickness:	2 oz

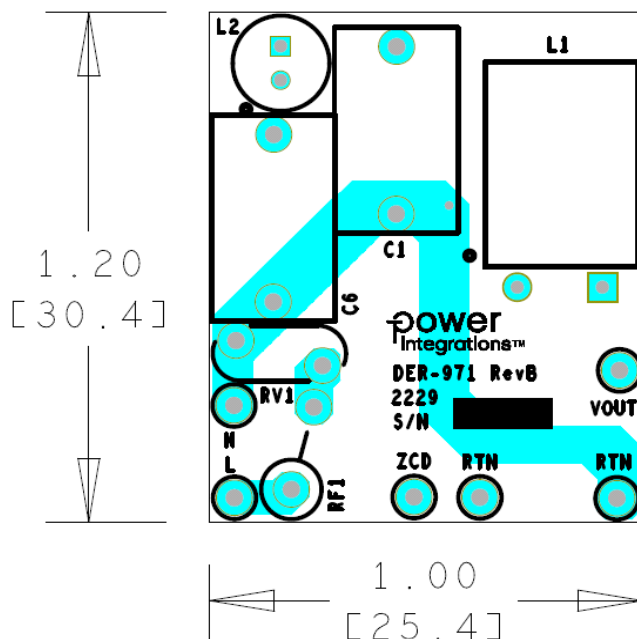


Figure 4 – Populated Circuit Board, Top View.

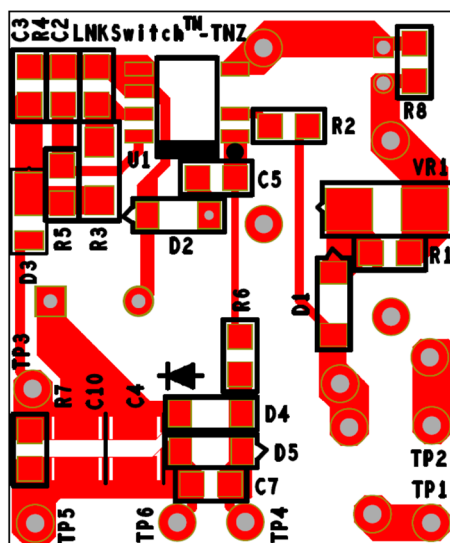


Figure 5 – Populated Circuit Board, Bottom View.

6 Bill of Materials

6.1 Electrical Parts

Item	Qty	Ref Des	Description	Mfg Part Number	Mfg
1	1	C1	0.68 μ F Film 125V 250V Polyester, Metallized Radial, (12.30 mm x 7.30 mm)	ECQ-E2684KB	Panasonic
2	1	C2	100 nF, 25 V, Ceramic, X7R, 0805	08053C104KAT2A	AVX
3	1	C3	10 μ F, \pm 10%, 16V, X7R, Ceramic, SMT, MLCC 0805	CL21B106KOQNNNE	Samsung
4	1	C4	47 μ F, Molded Tantalum, 10 V, 1411, 1210, 250 m Ω	TPSB476K010R0250	AVX
5	1	C5	100 pF, 100 V, Ceramic, COG, 0805	C0805C101J1GACTU	Kemet
6	1	C6	0.68 μ F Film 125V 250V Polyester, Metallized Radial, (12.30mm x 7.30mm)	ECQ-E2684KB	Panasonic
7	1	C10	47 μ F, Molded Tantalum, 10 V, 1411, 1210, 250 m Ω	TPSB476K010R0250	AVX
8	1	D1	1000V, 1 A, Standard Recovery, SOD-123FL	SM4007PL-TP	Micro Commercial
9	1	D2	Diode, Standard, 400 V, 1A, SMT SOD-123FL	ES1004FL_R1_00001	Panjit
10	1	D3	400 V, 1 A, Rectifier, Glass Passivated, POWERDI123	DFLR1400-7	Diodes, Inc.
11	1	D4	Diode, GEN PURP, 50 V, 1 A, SOD-123F, SOD123FL	SM4001PL-TP	Micro Commercial
12	1	D5	Diode, GEN PURP, 50 V, 1 A, SOD-123F, SOD123FL	SM4001PL-TP	Micro Commercial
13	1	L1	1000 μ H, 0.510 A	RLB9012-102KL	Bourns
14	1	L2	2.2 mH, 0.046 A, 20%	RL-5480-1-2200	Renco
15	1	R1	RES, 4.99 k Ω , 1%, 1/8 W, Thick Film, 0805	ERJ-6ENF4991V	Panasonic
16	1	R2	RES, 1.0 M Ω , 5%, 1/8 W, Thick Film, 0805	ERJ-6GEYJ105V	Panasonic
17	1	R3	RES, 2 k Ω , 1%, 1/4 W, Thick Film, 1206	ERJ-8ENF2001V	Panasonic
18	1	R4	RES, 39.2 k Ω , 1%, 1/8 W, Thick Film, 0805	ERJ-6ENF3922V	Panasonic
19	1	R5	RES, 33.2 k Ω , 1%, 1/8 W, Thick Film, 0805	ERJ-6ENF3322V	Panasonic
20	1	R6	RES, 100 k Ω , 5%, 1/8 W, Thick Film, 0805	ERJ-6GEYJ104V	Panasonic
21	1	R7	RES, 20 k Ω , 5%, 1/8 W, Thick Film, 0805	ERJ-6GEYJ203V	Panasonic
22	1	R8	RES, 4.7 k Ω , 5%, 1/8 W, Thick Film, 0805	ERJ-6GEYJ472V	Panasonic
23	1	RF1	RES, 8.2 Ω , 1 W, 5%, Fusible/Flame Proof Wire Wound	FKN1WSJR-52-8R2	Yageo
24	1	RV1	140 VAC, 12 J, 7 mm, RADIAL	V140LA2P	Littlefuse
25	1	U1	LinkSwitch-TNZ, SO8	LNK3302D	Power Integrations
26	1	VR1	Diode, ZENER, 10 V, \pm 5%, 1 W, DO-214AC, SMA	SMAZ10-13-F	Diodes, Inc.

6.2 Optional Part

Item	Qty	Ref Des	Description	Mfg Part Number	Mfg
1	1	C7	100 pF, 100 V, Ceramic, COG, 0805	C0805C101J1GACTU	Kemet
2	2	C1 C6	0.68 μ F Film 160 V 250 V Polyester (55 $^{\circ}$ C \sim 125 $^{\circ}$ C) (18.00 mm x 7.00 mm)	B32522C3684K189	EPCOS

6.3 Mechanical Parts

Item	Qty	Ref Des	Description	Mfg Part Number	Mfg
1	1	TP1	Test Point, BLK, Miniature THRU-HOLE MOUNT	5001	Keystone
2	1	TP2	Test Point, WHT, Miniature THRU-HOLE MOUNT	5002	Keystone
3	1	TP3	Test Point, RED, Miniature THRU-HOLE MOUNT	5000	Keystone
4	1	TP4	Test Point, BLUE, Miniature THRU-HOLE MOUNT	5117	Keystone
5	1	TP5	Test Point, BLK, Miniature THRU-HOLE MOUNT	5001	Keystone
6	1	TP6	Test Point, BLK, Miniature THRU-HOLE MOUNT	5001	Keystone



7 Design Spreadsheet

1	ACDC_LinkSwitchT NZ_Buck_052621; Rev.1.0; Copyright Power Integrations 2021	INPUT	INFO	OUTPUT	UNIT	ACDC LinkSwitch-TNZ Buck
2	ENTER APPLICATION VARIABLES					
3	LINE VOLTAGE RANGE			Custom		AC line voltage range
4	VACMIN	90.00		90.00	V	Minimum AC line voltage
5	VACMAX	132.00		132.00	V	Maximum AC line voltage
6	fL	60.00		60.00	Hz	AC mains frequency
7	LINE RECTIFICATION TYPE	H		H		Line rectification type: select "F" if full wave rectification or "H" if half wave rectification
8	VOUT	5.00		5.00	V	Output voltage
9	IOUT	0.050		0.050	A	Average output current
10	EFFICIENCY_ESTIMAT ED			0.80		Efficiency estimate at output terminals
11	EFFICIENCY_CALCULA TED			0.69		Calculated efficiency based on real components and operating point
12	POUT			0.25	W	Continuous output power
13	CIN			1.50	uF	Input capacitor
14	VMIN			90.6	V	Valley voltage of the rectified minimum AC line voltage
15	VMAX			186.7	V	Peak voltage of the maximum AC line voltage
16	INPUT STAGE RESISTANCE			10	Ohms	Input stage resistance in ohms (includes thermistor, filtering components, etc)
17	PLOSS_INPUTSTAGE			0.000	W	Maximum input stage loss
21	ENTER LINKSWITCH-TNZ VARIABLES					
22	OPERATION MODE			MDCM		Mostly continuous mode of operation
23	CURRENT LIMIT MODE	STD		STD		Choose 'RED' for reduced current limit or 'STD' for standard current limit
24	PACKAGE	NO		NO		Select the device package
25	DEVICE SERIES			SO-8C		Generic LinkSwitch-TNZ device
26	DEVICE CODE	LNK3302		LNK3302		Required LinkSwitch-TNZ device
27	ILIMITMIN			LNK3302D	A	Minimum current limit of the device
28	ILIMITTYP			0.126	A	Typical current limit of the device
29	ILIMITMAX			0.136	A	Maximum current limit of the device
30	RDSON			0.146	ohms	Primary switch on-time drain to source resistance at 100degC
31	FMIN			88.40	Hz	Minimum switching frequency
32	FSTYP			62000	Hz	Typical switching frequency
33	FSMAX			66000	Hz	Maximum switching frequency
34	BVDSS			725	V	Device breakdown voltage
38	SWITCH PARAMETERS					
39	VDSOON			2.00	V	Switch on-time drain to source voltage estimate
40	VDSOFF			196.0	V	Switch off-time drain-to-source voltage stress
41	DUTY			0.050		Maximum duty cycle
42	TIME_ON_MIN			0.717	us	Switch minimum on-time
43	IPED_SWITCH			0.000	A	Maximum switch pedestal current
44	IRMS_SWITCH			0.018	A	Maximum switch RMS current
45	PLOSS_SWITCH			0.048	W	Maximum switch loss
46	THERMAL RESISTANCE OF SWITCH			100	degC/ W	Net thermal resistance of the switch
47	T_RISE_SWITCH			4.8	degC	Maximum temperature rise of the switch in degrees Celsius
51	BUCK INDUCTOR PARAMETERS					
52	INDUCTANCE_MIN			900	uH	Minimum design inductance required for current delivery
53	INDUCTANCE_TYP	AUTO		1000	uH	Typical design inductance required for current delivery
54	INDUCTANCE_MAX			1100	uH	Maximum design inductance required for current delivery
55	TOLERANCE_INDUCTA NCE			10	%	Tolerance of the design inductance



56	DC RESISTANCE OF INDUCTOR			2.0	ohms	DC resistance of the buck inductor
57	FACTOR_KLOSS			0.50		Factor that accounts for "off-state" power loss to be supplied by inductor (usually between 50% to 66%)
58	IRMS_INDUCTOR			0.077	A	Maximum inductor RMS current
59	PLOSS_INDUCTOR			0.012	W	Maximum inductor losses
63	FREEWHEELING DIODE PARAMETERS					
64	VF_FREEWHEELING			0.70	V	Forward voltage drop across the freewheeling diode
65	PIV_RATING			400.0	V	Peak inverse voltage rating of the freewheeling diode
66	TRR			75	ns	Reverse recovery time of the freewheeling diode
67	PIV_CALCULATED			233.3	V	Computed peak inverse voltage across the freewheeling diode
68	IRMS_DIODE			0.076	A	Maximum diode RMS current
69	PLOSS_DIODE			0.061	W	Maximum freewheeling diode loss
70	RECOMMENDED DIODE			MUR140		Recommended freewheeling diode
74	BIAS/FEEDBACK PARAMETERS					
75	VF_BIAS			0.70	V	Forward voltage drop of the bias diode
76	RBIAS	39200		39200	Ohms	Bias resistor (connected across FB and S pin). Results into IFB_BIAS value of 49.751 uA
77	RBP			N/A	Ohms	BP pin resistor
78	CBP			0.1	uF	BP pin capacitor
79	RFB			30100	Ohms	Feedback resistor
80	CFB			10	uF	Feedback capacitor
81	C_SOFTSTART			N/A	uF	No soft-start capacitor required
82	PLOSS_FEEDBACK			0.000	W	Maximum feedback component losses
86	X-CAPACITOR DISCHARGE COMPONENTS					
87	XCAP_REQUIRED	NO		NO		Select whether an X-capacitor is required or not
88	XCAP			N/A	nF	X-capacitor in the input
89	TOLERANCE_RZ	0.05		N/A		Tolerance of the X-capacitor discharge resistors
90	RZ1			N/A	MOhms	X-capacitor discharge resistor connected from the input line to Z1 pin of LinkSwitch-TNZ device
91	RZ2			N/A	MOhms	X-capacitor discharge resistor connected from the input neutral to Z2 pin of LinkSwitch-TNZ device
92	t_XCAP_DISCHARGE			N/A	sec	Actual time (worst-case) to discharge the X-capacitor to 60 V after AC input disconnection
96	OUTPUT CAPACITOR					
97	OUTPUT VOLTAGE RIPPLE			100	mV	Desired output voltage ripple
98	IRMS_COUT			0.059	A	Maximum output capacitor RMS current
99	PLOSS_COUT			0.003	W	Maximum output capacitor power loss
100	ESR_COUT			778	mOhms	ESR of the output capacitor



8 Performance Data

8.1 Efficiency

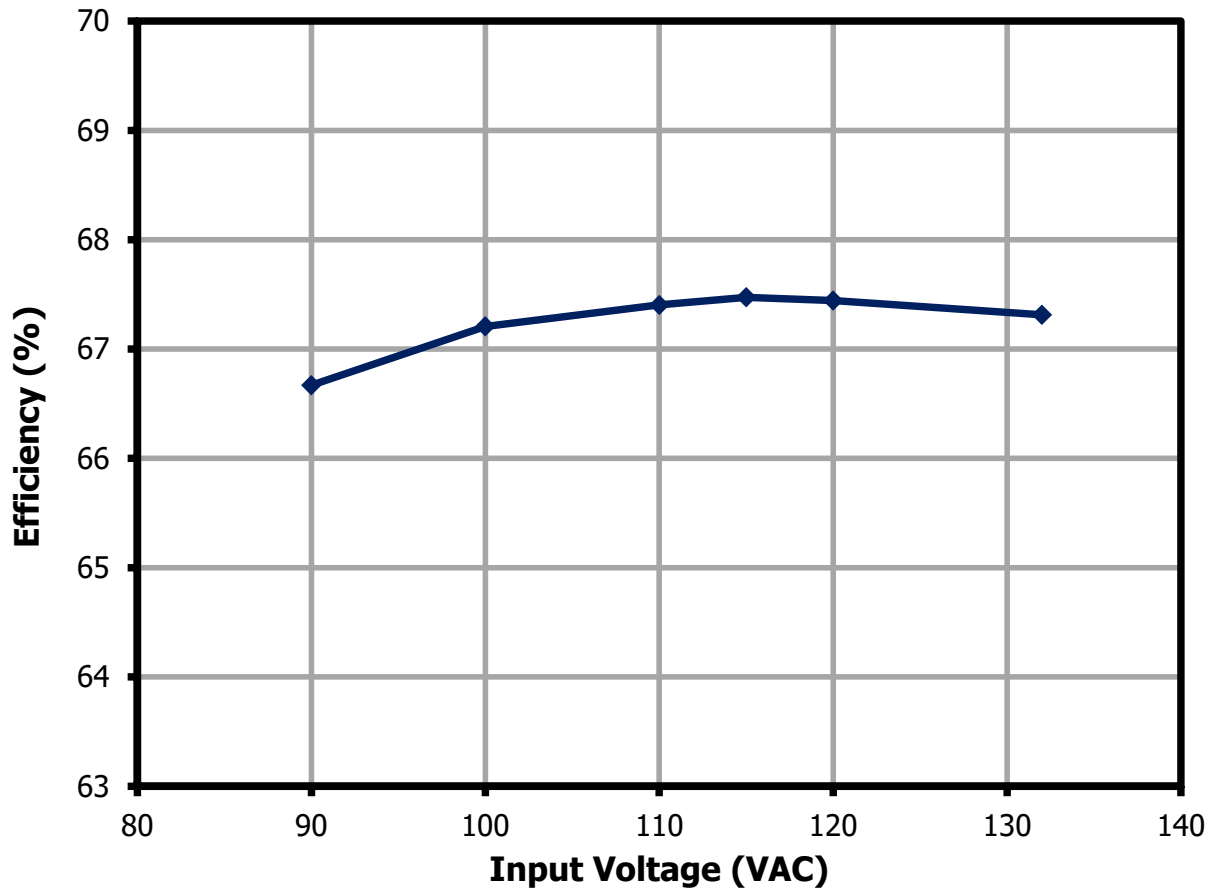


Figure 6 – Full Load Efficiency vs. Line.

8.2 No-Load Input Current

Test Condition: Soak for 5 minutes each line and use Fluke DMM.

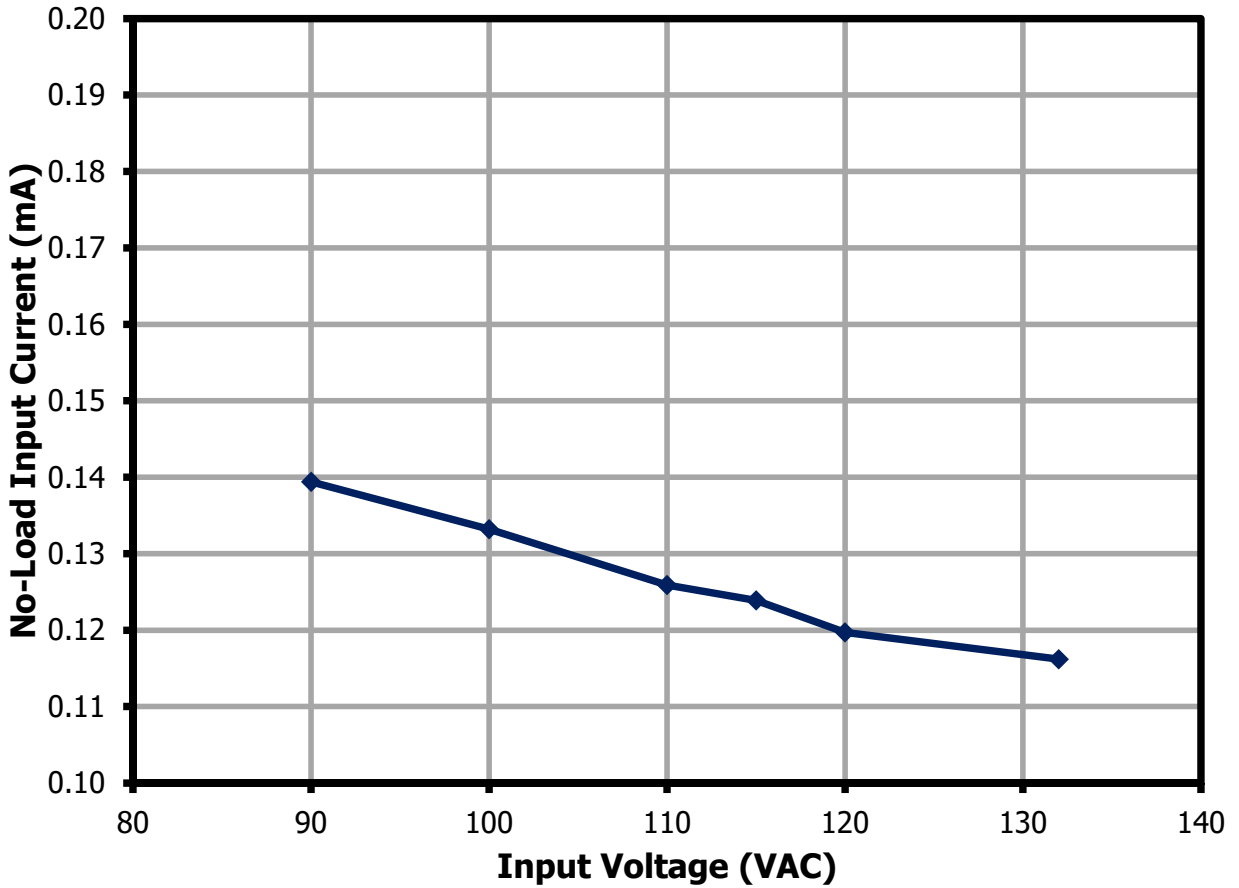


Figure 7 – No-Load Input Current vs. Line.

8.3 Line Regulation at Different Ambient Temperatures

8.3.1 Line Regulation Performance at Room Ambient Temperature

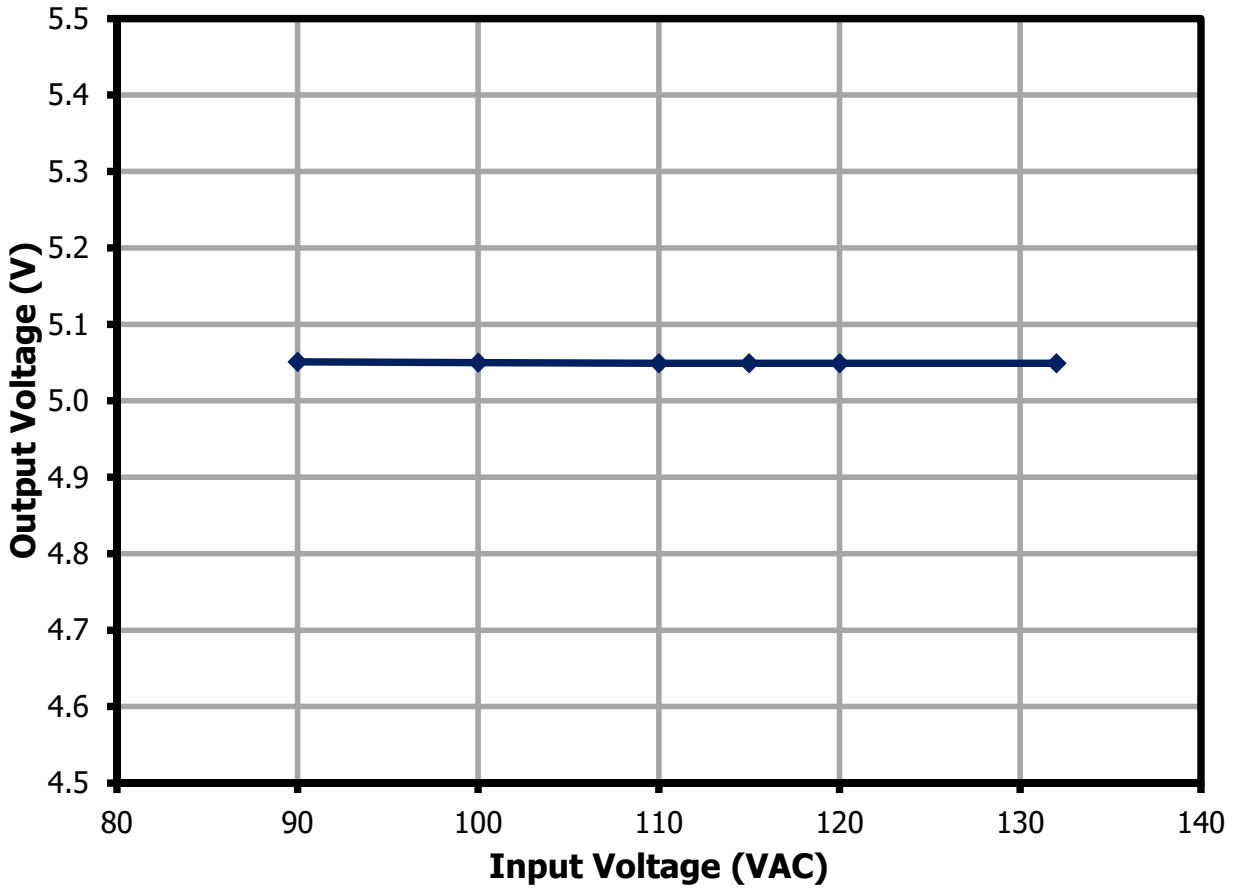


Figure 8 – Output Voltage vs. Line Voltage.

8.3.2 Line Regulation Performance at 70 °C Ambient Temperature

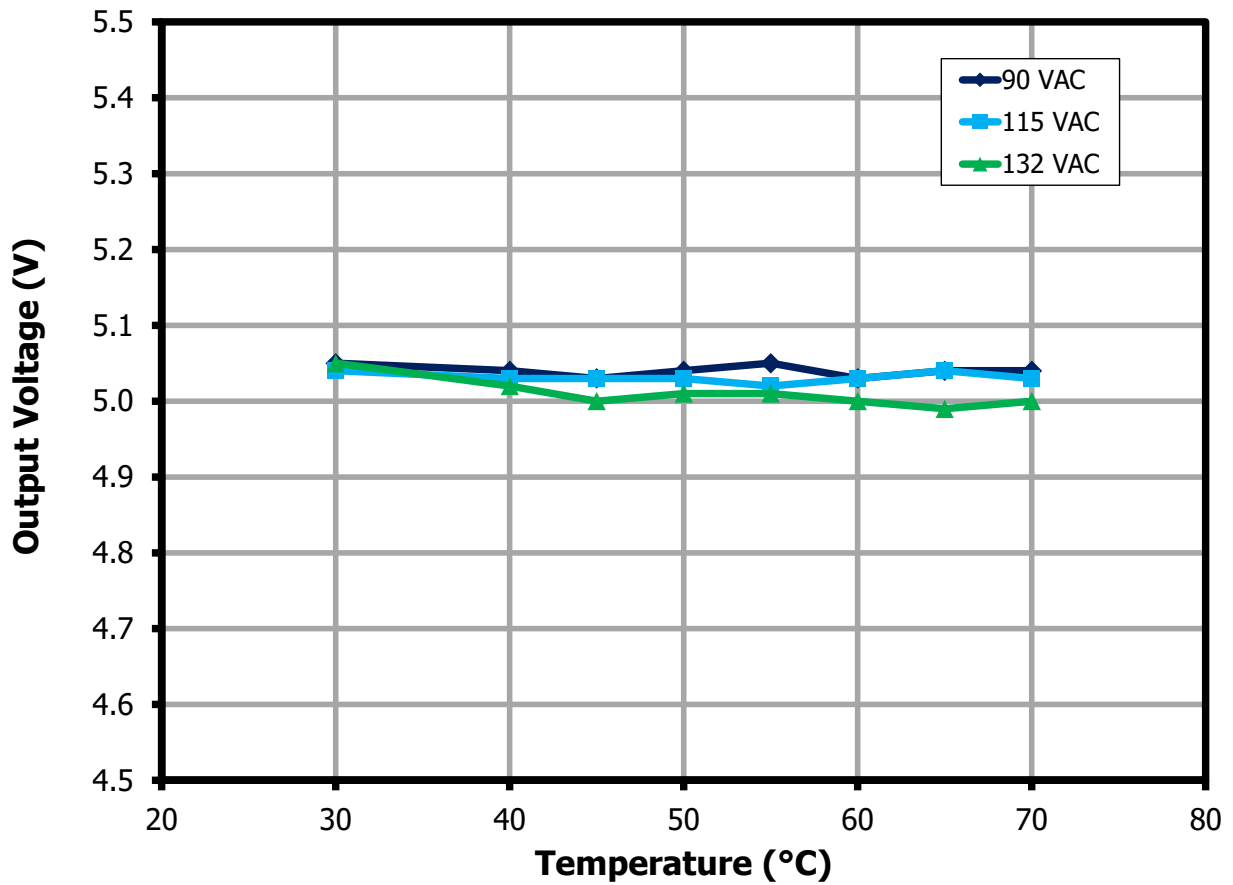


Figure 9 – Output Voltage vs. Temperature.

8.3.3 Line Regulation Performance at -40°C Ambient Temperature

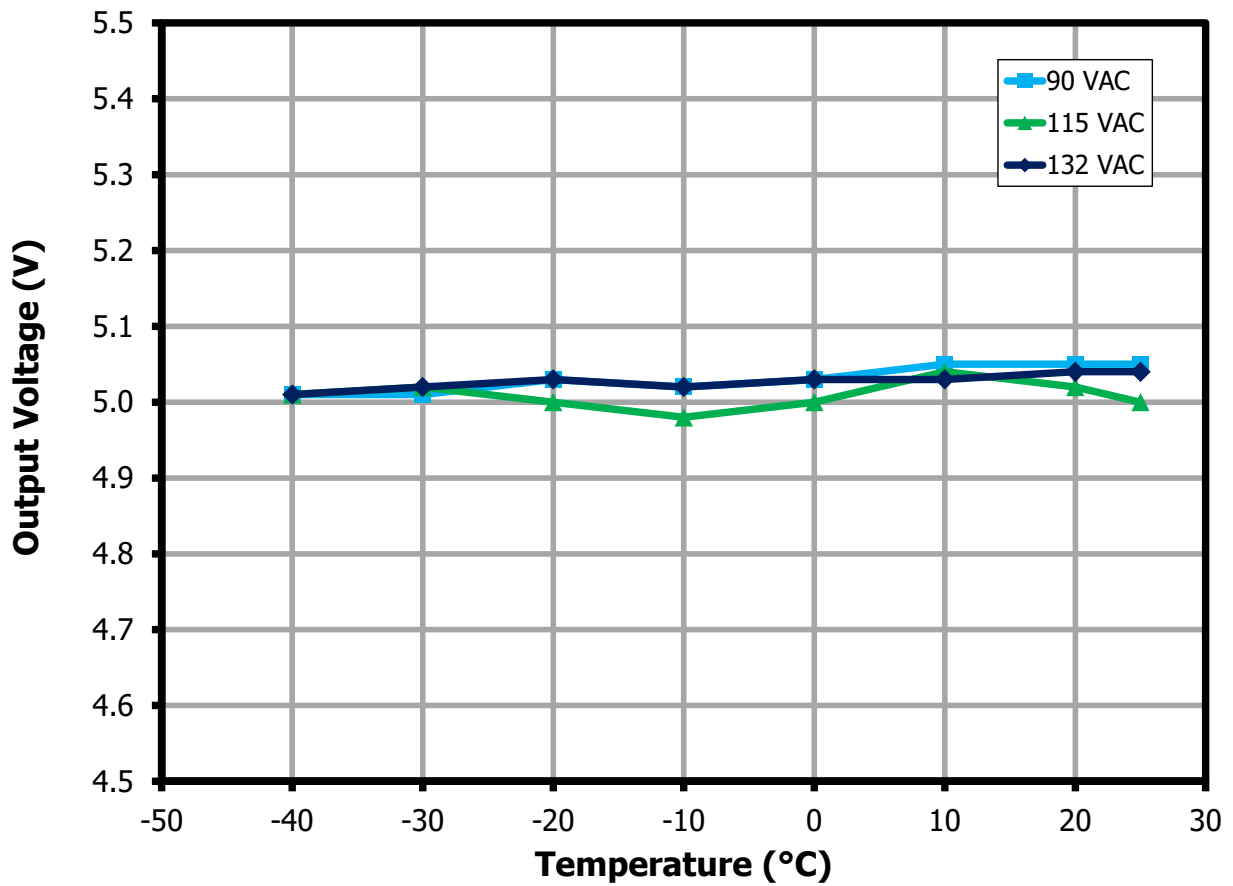


Figure 10 – Output Voltage vs. Temperature.

8.4 Load Regulation

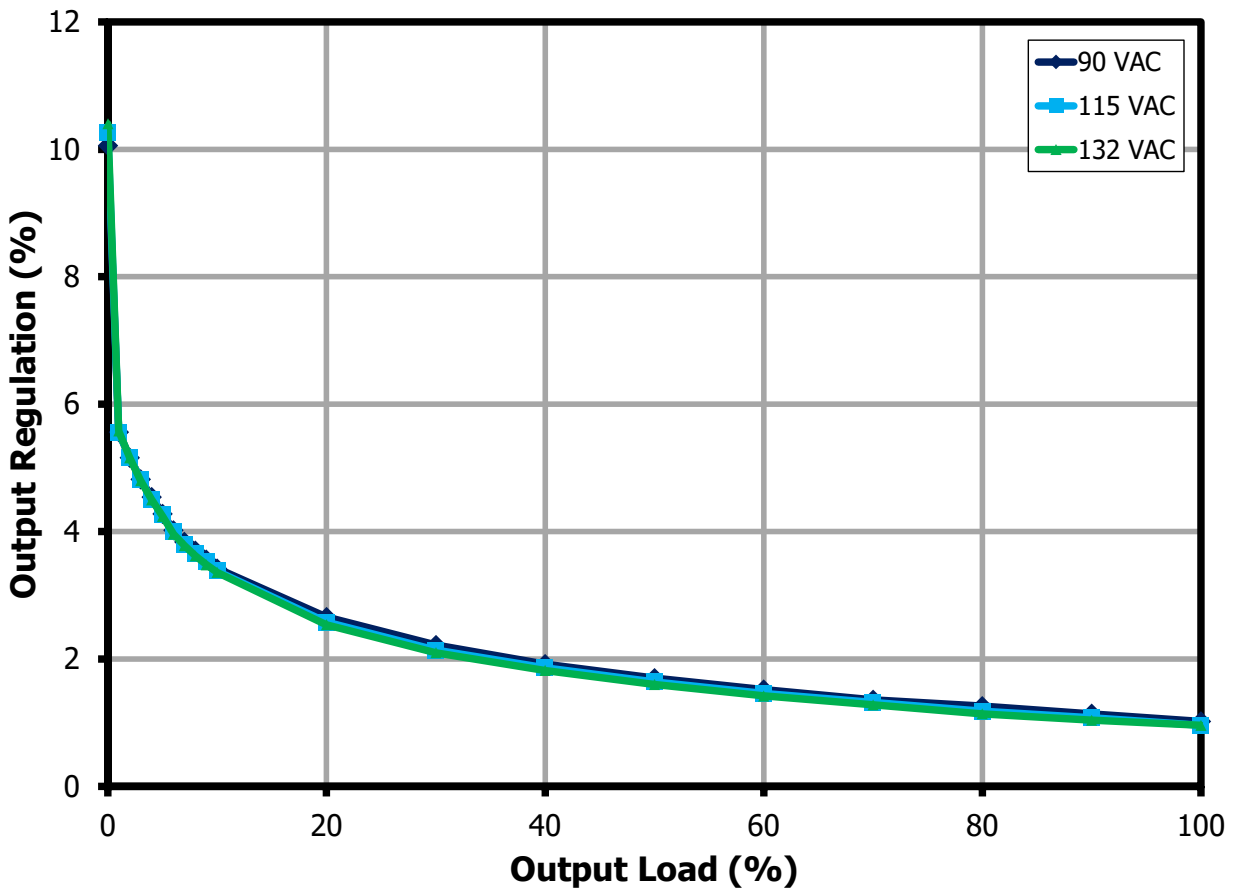


Figure 11 – Output Voltage vs. Percent Load.

9 Waveforms

9.1 Zero-Crossing Detection

9.1.1 Zero-Crossing Detection at Normal Operation

9.1.1.1 100% Load

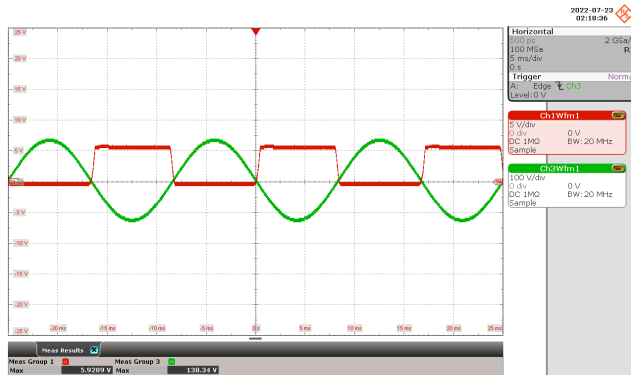


Figure 12 – 90 VAC 60 Hz.
 CH1: ZCD, 5 V / div., 5 ms / div.
 CH3: V_{IN} , 100 V / div., 5 ms / div.

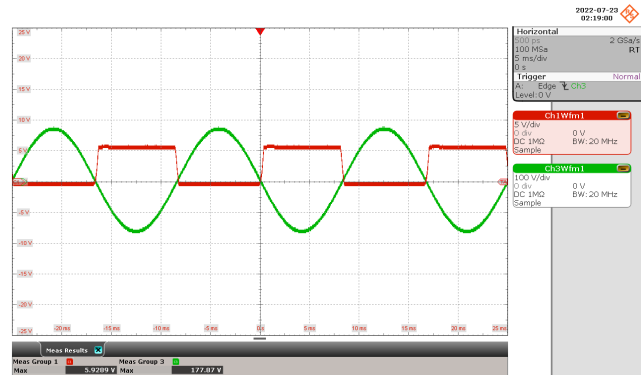


Figure 13 – 115 VAC 60 Hz.
 CH1: ZCD, 5 V / div., 5 ms / div.
 CH3: V_{IN} , 100 V / div., 5 ms / div.

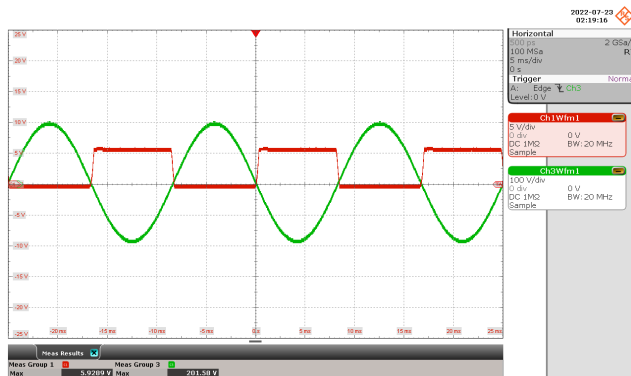


Figure 14 – 132 VAC 50 Hz.
 CH1: ZCD, 5 V / div., 5 ms / div.
 CH3: V_{IN} , 100 V / div., 5 ms / div.

9.1.1.2 0% Load

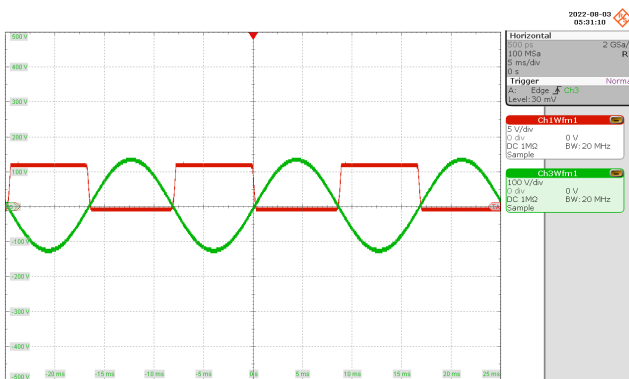


Figure 15 – 90 VAC 60 Hz.
 CH1: ZCD, 5 V / div., 5 ms / div.
 CH3: V_{IN} , 100 V / div., 5 ms / div.

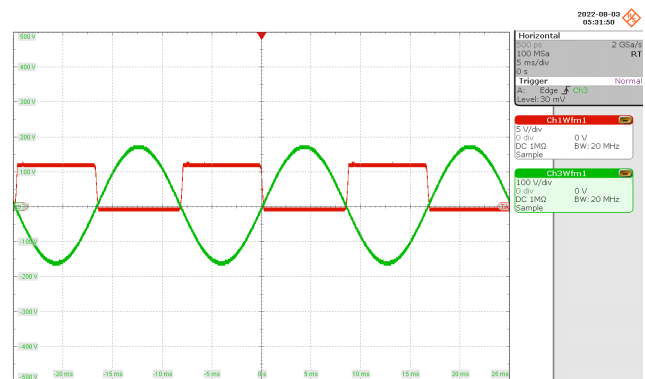


Figure 16 – 115 VAC 60 Hz.
 CH1: ZCD, 5 V / div., 5 ms / div.
 CH3: V_{IN} , 100 V / div., 5 ms / div.

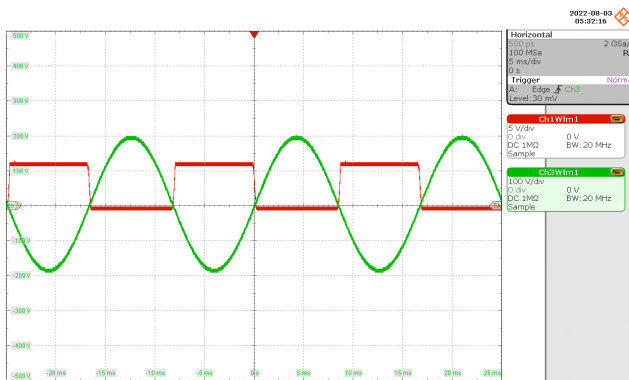


Figure 17 – 132 VAC 60 Hz.
 CH1: ZCD, 5 V / div., 5 ms / div.
 CH3: V_{IN} , 100 V / div., 5 ms / div.

9.1.2 Zero-Crossing Detection at Start-up

9.1.2.1 0° Start-up Phase

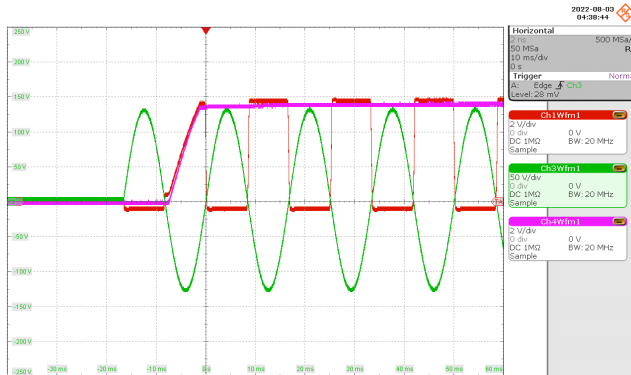


Figure 18 – 90 VAC 60 Hz, No-Load.
 CH1: ZCD, 2 V / div., 10 ms / div.
 CH3: V_{IN} , 50 V / div., 10 ms / div.
 CH4: V_{OUT} , 2 V / div., 10 ms / div.

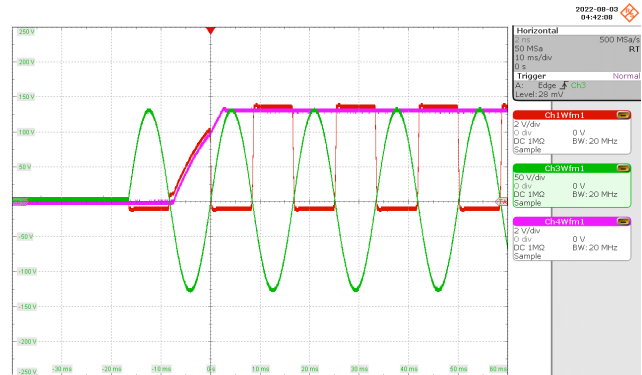


Figure 19 – 90 VAC 60 Hz, Full Load.
 CH1: ZCD, 2 V / div., 10 ms / div.
 CH3: V_{IN} , 50 V / div., 10 ms / div.
 CH4: V_{OUT} , 2 V / div., 10 ms / div.

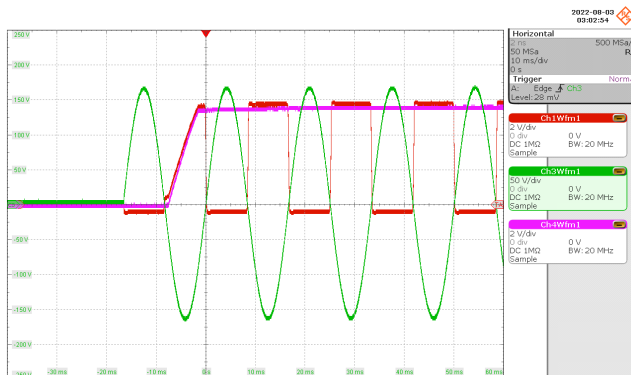


Figure 20 – 115 VAC 50 Hz, No-Load.
 CH1: ZCD, 2 V / div., 10 ms / div.
 CH3: V_{IN} , 50 V / div., 10 ms / div.
 CH4: V_{OUT} , 2 V / div., 10 ms / div.

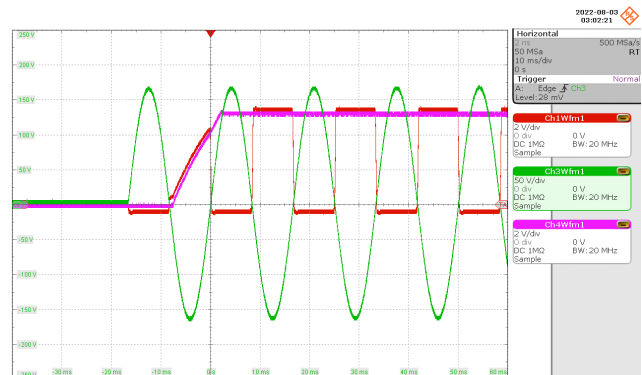


Figure 21 – 115 VAC 50 Hz, Full Load.
 CH1: ZCD, 2 V / div., 10 ms / div.
 CH3: V_{IN} , 50 V / div., 10 ms / div.
 CH4: V_{OUT} , 2 V / div., 10 ms / div.

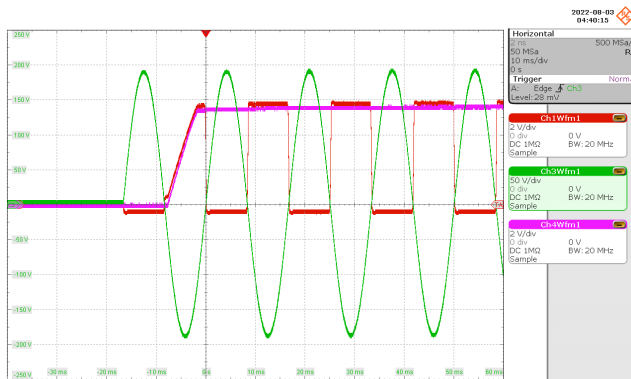


Figure 22 – 132 VAC 60 Hz, No-Load.
 CH1: ZCD, 2 V / div., 10 ms / div.
 CH3: V_{IN} , 50 V / div., 10 ms / div.
 CH4: V_{OUT} , 2 V / div., 10 ms / div.

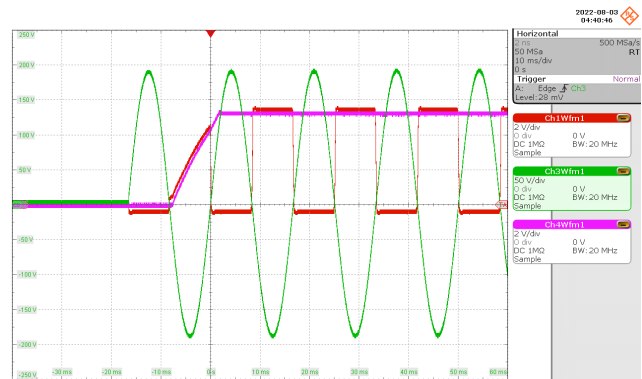


Figure 23 – 132 VAC 60 Hz, Full Load.
 CH1: ZCD, 2 V / div., 10 ms / div.
 CH3: V_{IN} , 50 V / div., 10 ms / div.
 CH4: V_{OUT} , 2 V / div., 10 ms / div.

9.1.2.2 90° Start-up Phase

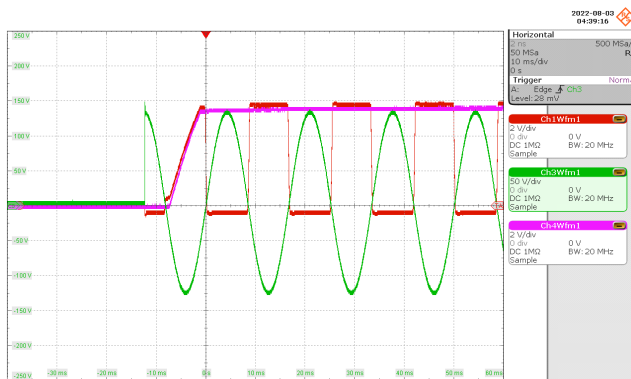


Figure 24 – 90 VAC 60 Hz, No-Load.
 CH1: ZCD, 2 V / div., 10 ms / div.
 CH3: V_{IN} , 50 V / div., 10 ms / div.
 CH4: V_{OUT} , 2 V / div., 10 ms / div.

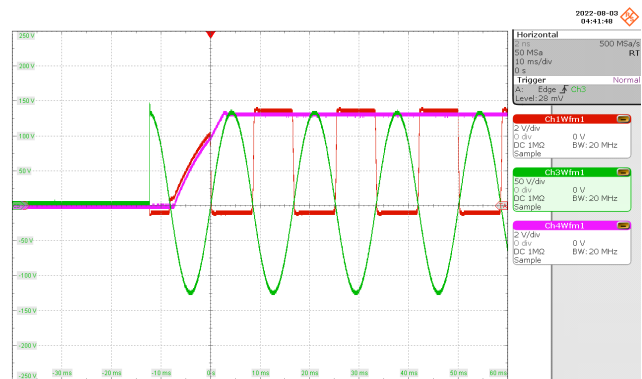


Figure 25 – 90 VAC 60 Hz, Full Load.
 CH1: ZCD, 2 V / div., 10 ms / div.
 CH3: V_{IN} , 50 V / div., 10 ms / div.
 CH4: V_{OUT} , 2 V / div., 10 ms / div.

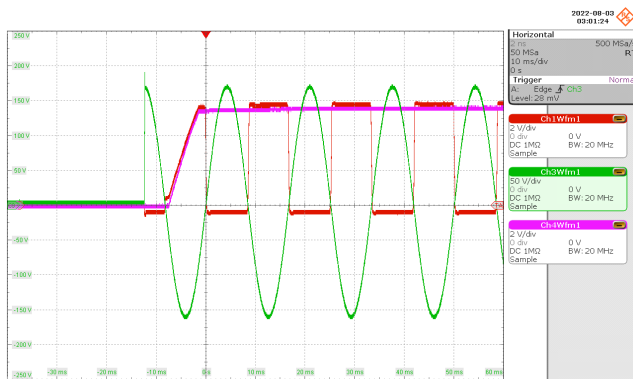


Figure 26 – 115 VAC 60 Hz, No-Load.
 CH1: ZCD, 2 V / div., 10 ms / div.
 CH3: V_{IN} , 50 V / div., 10 ms / div.
 CH4: V_{OUT} , 2 V / div., 10 ms / div.

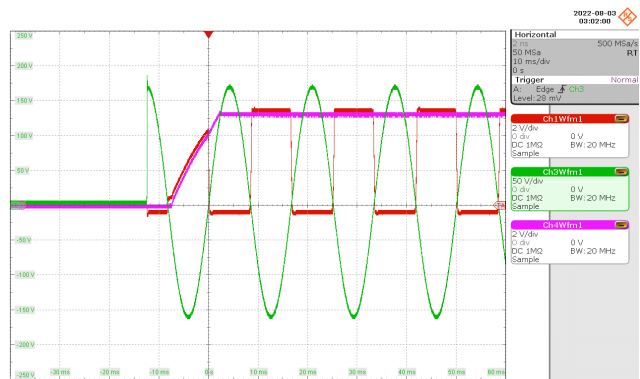


Figure 27 – 115 VAC 60 Hz, Full Load.
 CH1: ZCD, 2 V / div., 10 ms / div.
 CH3: V_{IN} , 50 V / div., 10 ms / div.
 CH4: V_{OUT} , 2 V / div., 10 ms / div.

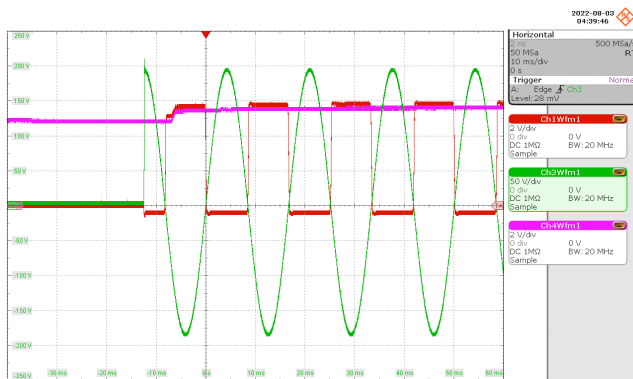


Figure 28 – 132 VAC 60 Hz, No-Load.
 CH1: ZCD, 2 V / div., 10 ms / div.
 CH3: V_{IN} , 50 V / div., 10 ms / div.
 CH4: V_{OUT} , 2 V / div., 10 ms / div.

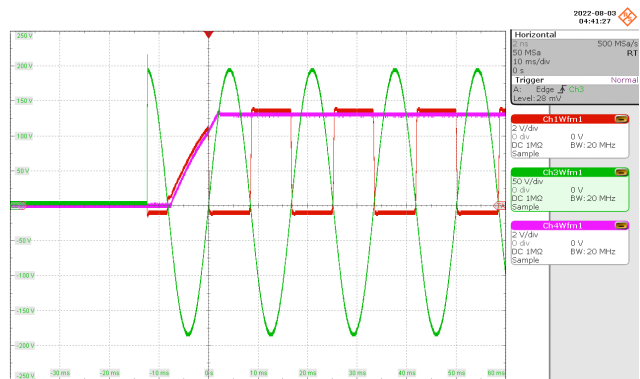


Figure 29 – 132 VAC 60 Hz, Full Load.
 CH1: ZCD, 2 V / div., 10 ms / div.
 CH3: V_{IN} , 50 V / div., 10 ms / div.
 CH4: V_{OUT} , 2 V / div., 10 ms / div.

9.1.3 Zero Crossing Detection Delay

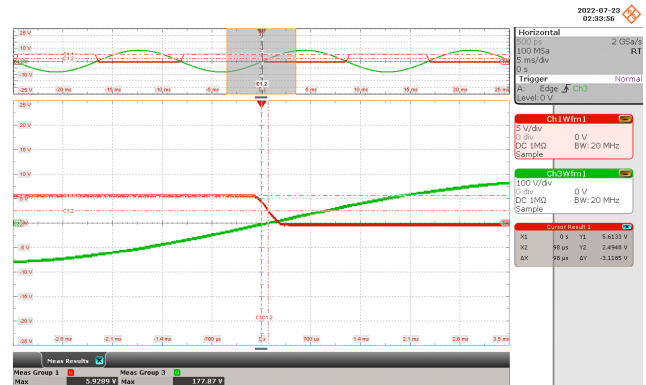
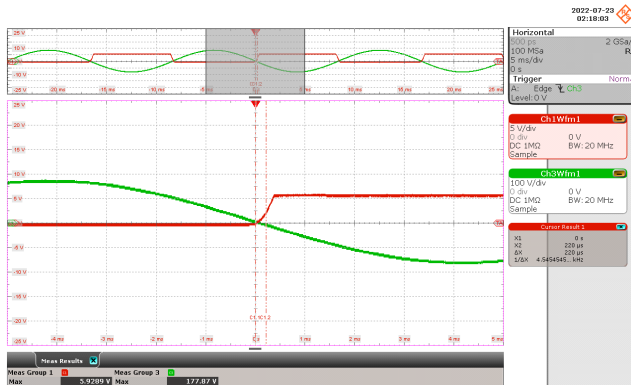


Figure 30 – 115 VAC 60 Hz.
 CH1: ZCD, 5 V / div., 5 ms / div.
 CH2: V_{IN} , 100 V / div., 5 ms / div.
 Rising Edge Delay = 220 μ s.

Figure 31 – 115 VAC 60 Hz.
 CH1: ZCD, 5 V / div., 5 ms / div.
 CH2: V_{IN} , 100 V / div., 5 ms / div.
 Falling Edge Delay = 98 μ s.

9.2 Output Voltage at Start-up

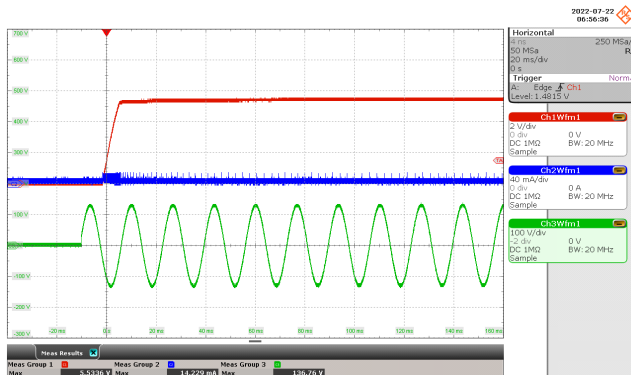


Figure 32 – 90 VAC 60 Hz, No-load.
 CH1: V_{OUT} , 2 V / div., 20 ms / div.
 CH2: I_{OUT} , 40 mA V / div., 20 ms / div.
 CH3: V_{IN} , 100 V / div., 20 ms / div.

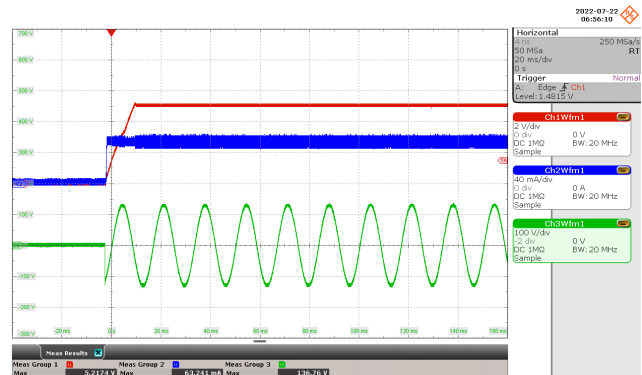


Figure 33 – 90 VAC 60 Hz, Full load.
 CH1: V_{OUT} , 2 V / div., 20 ms / div.
 CH2: I_{OUT} , 40 mA V / div., 20 ms / div.
 CH3: V_{IN} , 100 V / div., 20 ms / div.

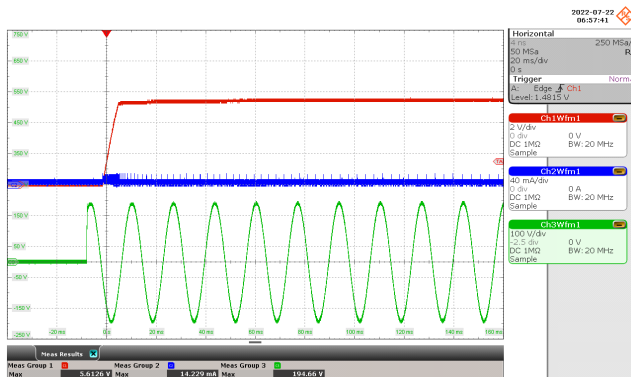


Figure 34 – 132 VAC 60 Hz, No-load.
 CH1: V_{OUT} , 2 V / div., 20 ms / div.
 CH2: I_{OUT} , 40 mA V / div., 20 ms / div.
 CH3: V_{IN} , 100 V / div., 20 ms / div.

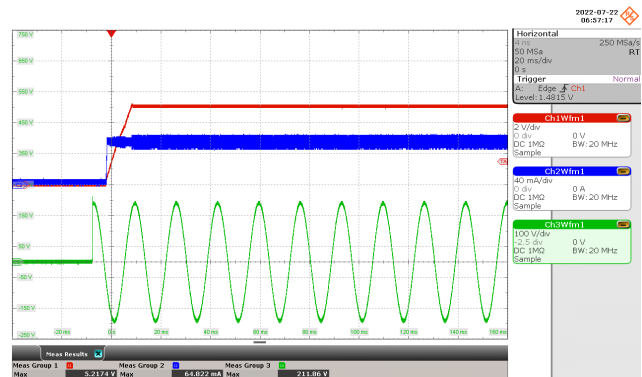


Figure 35 – 132 VAC 60 Hz, Full load.
 CH1: V_{OUT} , 2 V / div., 20 ms / div.
 CH2: I_{OUT} , 40 mA V / div., 20 ms / div.
 CH3: V_{IN} , 100 V / div., 20 ms / div.

9.3 Switching Waveforms

9.3.1 Primary MOSFET Drain-Source Voltage and Current at Normal Operation

9.3.1.1 100% Load

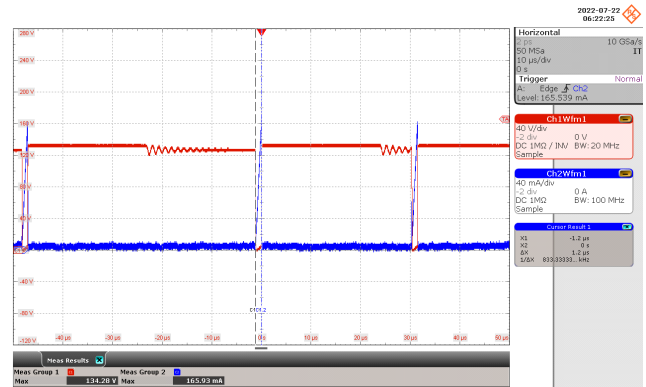
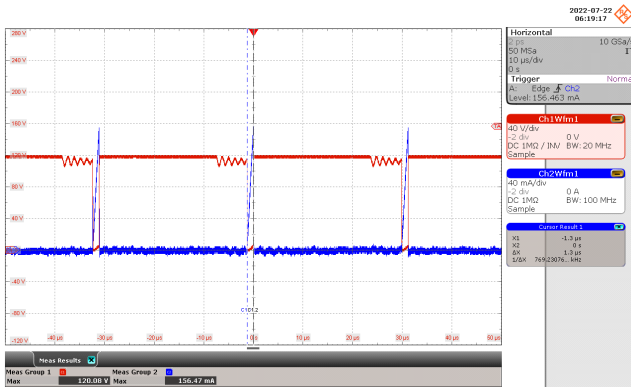


Figure 36 – 90 VAC 60 Hz.
 CH1: V_{DS} , 40 V / div., 10 µs / div.
 CH2: I_{DS} , 40 mA / div., 10 µs / div.
 $V_{DS(MAX)}$ = 120.08 V.
 $I_{DS(MAX)}$ = 156.47 mA.

Figure 37 – 115 VAC 60 Hz.
 CH1: V_{DS} , 40 V / div., 10 µs / div.
 CH2: I_{DS} , 40 mA / div., 10 µs / div.
 $V_{DS(MAX)}$ = 132.28 V.
 $I_{DS(MAX)}$ = 165.93 mA.

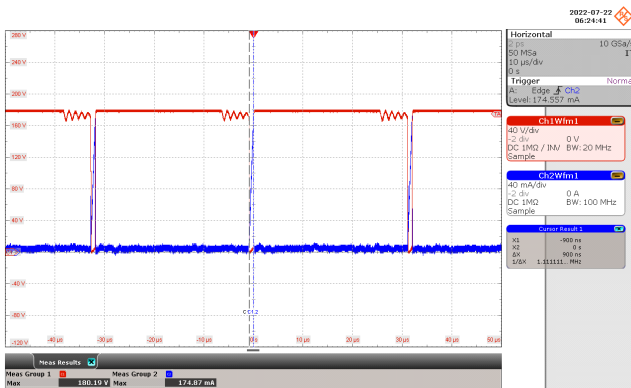


Figure 38 – 132 VAC 60 Hz.
 CH1: V_{DS} , 40 V / div., 10 µs / div.
 CH2: I_{DS} , 40 mA / div., 10 µs / div.
 $V_{DS(MAX)}$ = 180.19 V.
 $I_{DS(MAX)}$ = 174.87 mA.

9.3.1.2 0% Load

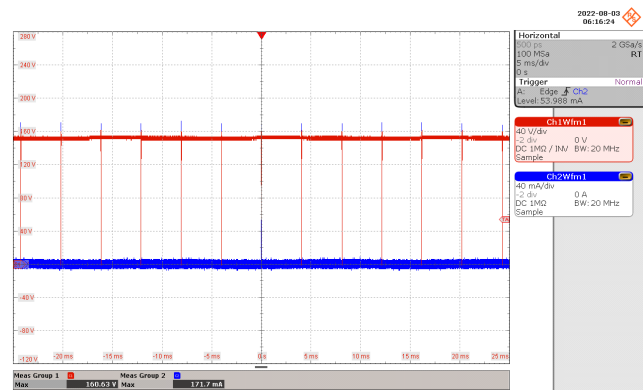
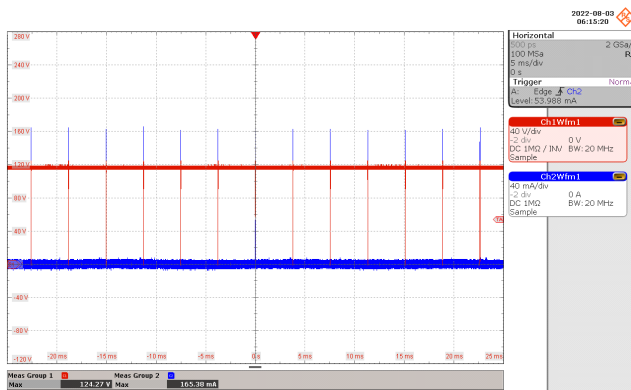


Figure 39 – 90 VAC 60 Hz.
 CH1: V_{DS} , 40 V / div., 5 ms / div.
 CH2: I_{DS} , 40 mA / div., 5 ms / div.
 $V_{DS(MAX)} = 124.27$ V.
 $I_{DS(MAX)} = 165.38$ mA.

Figure 40 – 115 VAC 60 Hz.
 CH1: V_{DS} , 40 V / div., 5 ms / div.
 CH2: I_{DS} , 40 mA / div., 5 ms / div.
 $V_{DS(MAX)} = 160.63$ V.
 $I_{DS(MAX)} = 171.7$ mA.

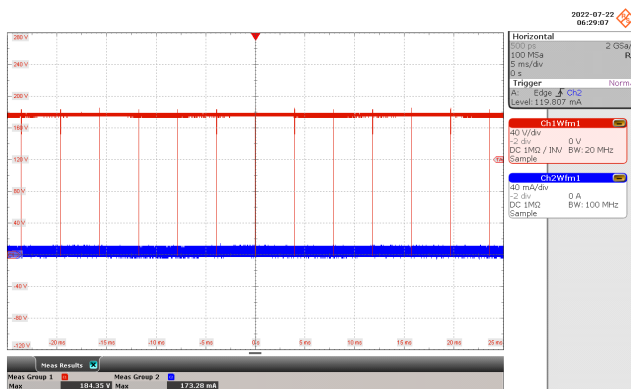


Figure 41 – 132 VAC 60 Hz.
 CH1: V_{DS} , 40 V / div., 5 ms / div.
 CH2: I_{DS} , 40 mA / div., 5 ms / div.
 $V_{DS(MAX)} = 184.35$ V.
 $I_{DS(MAX)} = 173.28$ mA.

9.3.2 Primary MOSFET Drain-Source Voltage and Current at Start-up Operation

9.3.2.1 100% Load

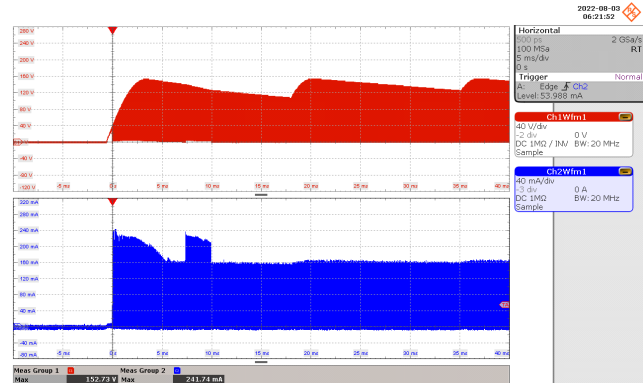
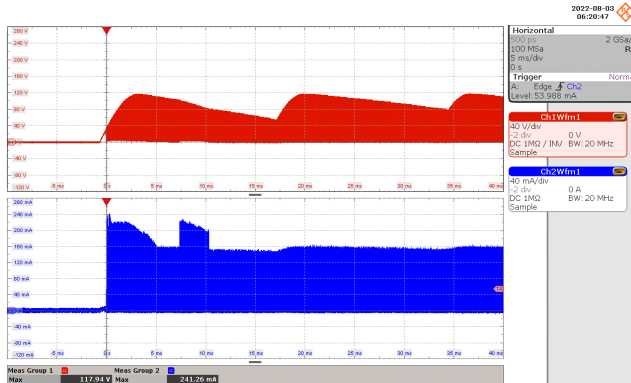


Figure 42 – 90 VAC 60 Hz.

CH1: V_{DS} , 40 V / div., 5 ms / div.
 CH2: I_{DS} , 40 mA / div., 5 ms / div.
 $V_{DS(MAX)} = 117.94$ V.
 $I_{DS(MAX)} = 241.26$ mA.

Figure 43 – 115 VAC 60 Hz.

CH1: V_{DS} , 40 V / div., 5 ms / div.
 CH2: I_{DS} , 40 mA / div., 5 ms / div.
 $V_{DS(MAX)} = 152.73$ V.
 $I_{DS(MAX)} = 241.74$ mA.

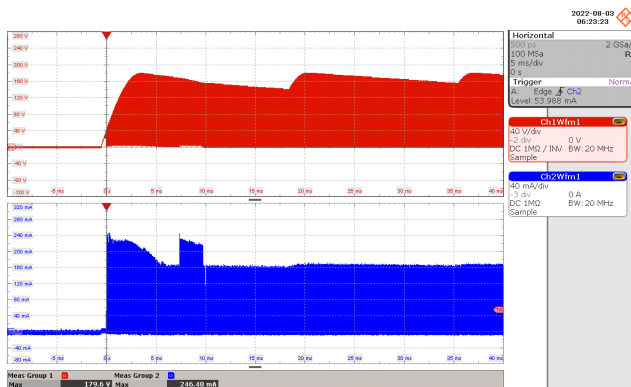


Figure 44 – 90 VAC 60 Hz.

CH1: V_{DS} , 40 V / div., 5 ms / div.
 CH2: I_{DS} , 40 mA / div., 5 ms / div.
 $V_{DS(MAX)} = 179.6$ V.
 $I_{DS(MAX)} = 246.48$ mA.

9.3.2.2 0% Load

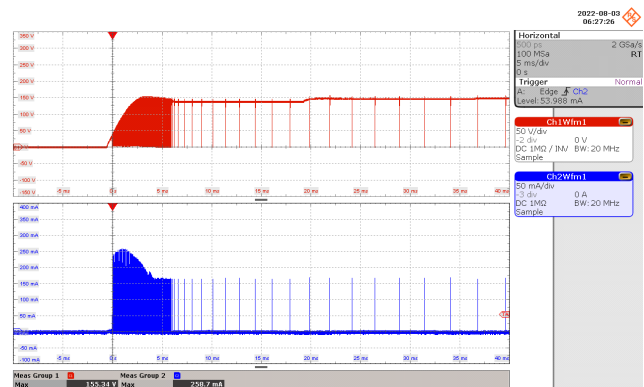
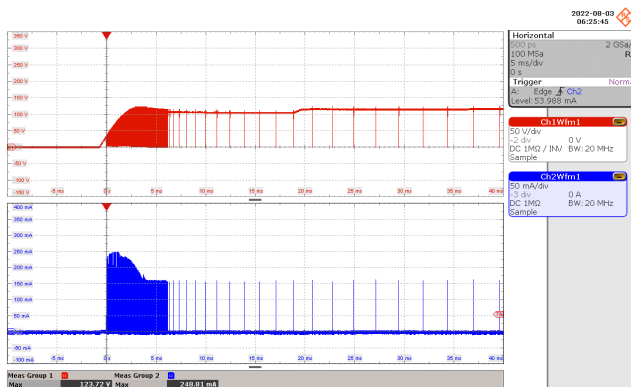


Figure 45 – 90 VAC 60 Hz.
 CH1: V_{DS} , 50 V / div., 5 ms / div.
 CH2: I_{DS} , 50 mA / div., 5 ms / div.
 $V_{DS(MAX)} = 123.72$ V.
 $I_{DS(MAX)} = 248.81$ mA.

Figure 46 – 115 VAC 60 Hz.
 CH1: V_{DS} , 50 V / div., 5 ms / div.
 CH2: I_{DS} , 50 mA / div., 5 ms / div.
 $V_{DS(MAX)} = 155.34$ V.
 $I_{DS(MAX)} = 258.7$ mA.

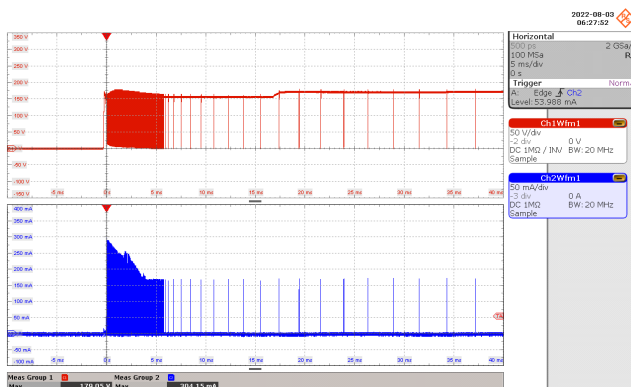


Figure 47 – 132 VAC 60 Hz.
 CH1: V_{DS} , 50 V / div., 5 ms / div.
 CH2: I_{DS} , 50 mA / div., 5 ms / div.
 $V_{DS(MAX)} = 179.05$ V.
 $I_{DS(MAX)} = 304.15$ mA.

10 Thermal Performance

Test Condition: This was performed inside a thermal chamber, and the DUT is contained within a metal box. The DUT was soaked for 2 hours each line, exposed to high ambient temperature (70 °C) and room temperature, and the results were recorded using a thermocouple and datalogger (GL840 GRAPHTEC).

10.1 Test Set-up



Figure 48 – Thermal Chamber Test Set-up.

10.1.1 Thermal Performance (70 °C Ambient Temperature)

Full Load (5 V 50 mA) 70 °C Ambient		
Component	Case Temperature (°C)	
	90 VAC	132 VAC
VR1	54.5	53.2
Freewheeling Diode	55.3	54.8
Output Inductor	53.9	53.6
Input Capacitor	52.9	52.2
LinkSwitch-TNZ	54.3	53.9

10.1.2 Thermal Performance (-40 °C Ambient Temperature)

Full Load (5 V 50 mA) -40 °C Ambient		
Component	Case Temperature (°C)	
	90 VAC	132 VAC
VR1	-34.1	-35.6
Freewheeling Diode	-32.5	-33.4
Output Inductor	-34.9	-35.6
Input Capacitor	-35.7	-36.6
LinkSwitch-TNZ	-34.9	-35.7

10.1.3 Thermal Performance (70 °C Ambient Temperature)

Full Load (5 V 50 mA) 70 °C Ambient		
Component	Case Temperature (°C)	
	90 VAC	132 VAC
VR1	71	70.4
Freewheeling Diode	71.5	71.6
Output Inductor	70.3	70.6
Input Capacitor	69.3	69.4
LinkSwitch-TNZ	70.9	71

10.1.4 Thermal Performance (Room Ambient Temperature)

Full Load (5 V 50 mA) Room Temperature		
Component	Case Temperature (°C)	
	90 VAC	132 VAC
VR1	29.05	27.8
Freewheeling Diode	29.05	29.05
Output Inductor	27.6	27.6
Input Capacitor	26.55	26.05
LinkSwitch-TNZ	28.05	28

11 Conducted EMI

11.1 Test Set-up

EMI measurement was done using a resistor load.

11.2 Equipment and Load Used

1. Rohde and Schwarz ENV216 two-line V-network.
2. Rohde and Schwarz ESRP EMI test receiver.
3. Variable voltage transformer set at 115 VAC

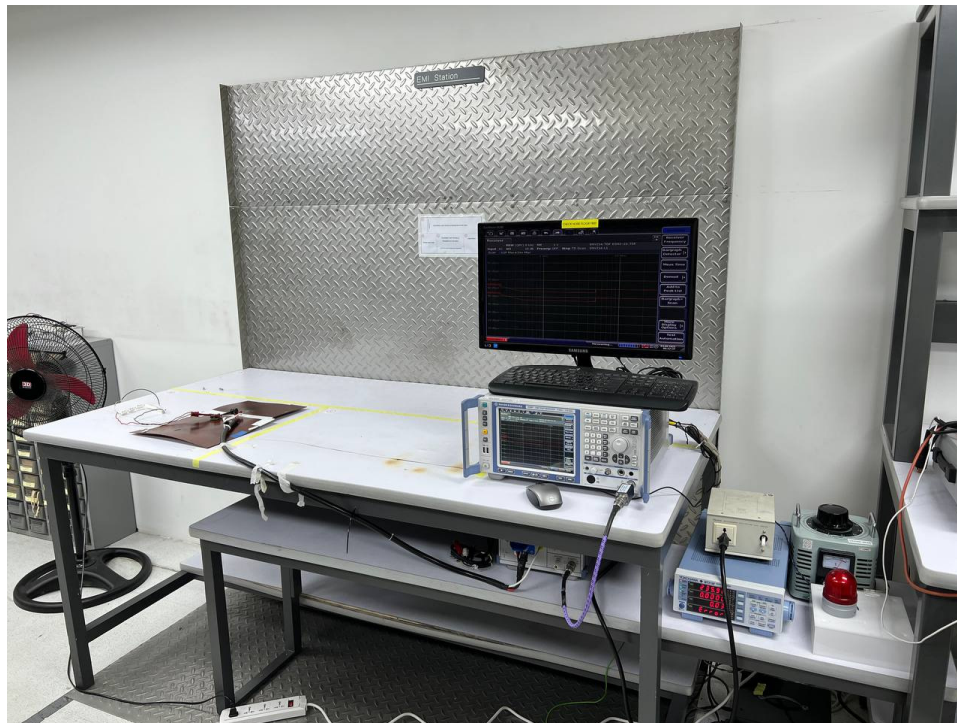
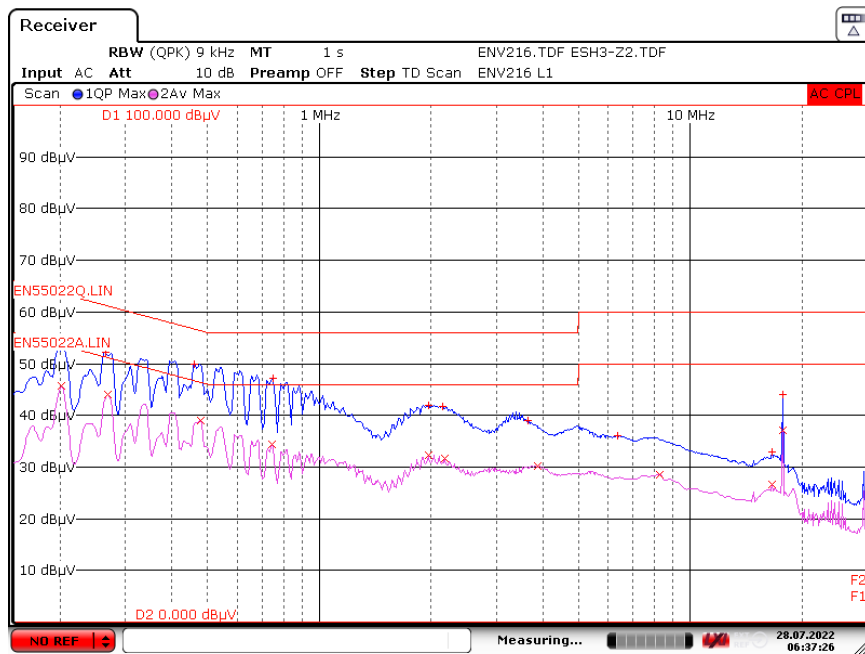


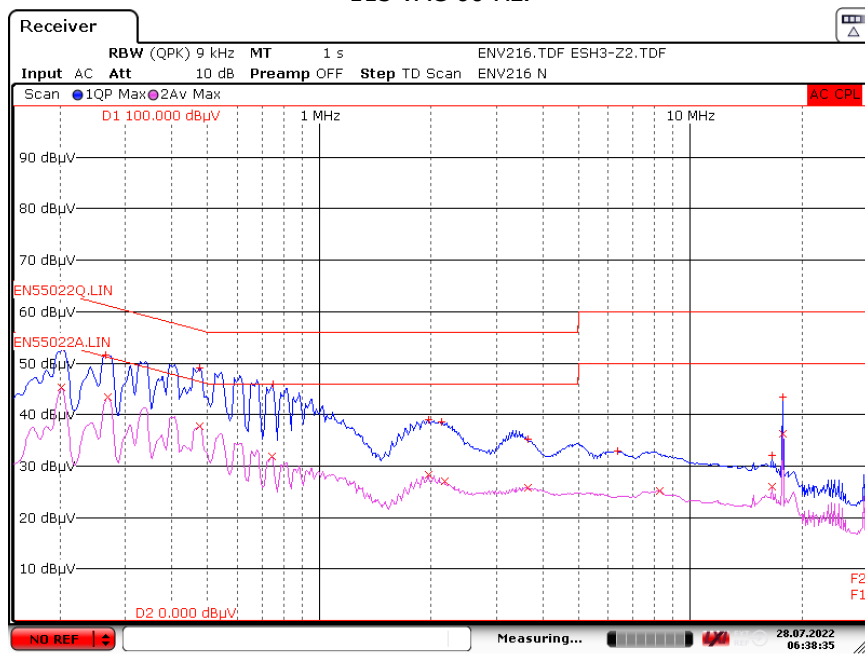
Figure 49 – Conducted EMI Test Set-up.

11.3 Conducted EMI Test Results



Date: 28.JUL.2022 06:37:26

Figure 50 – LINE.
115 VAC 60 Hz.



Date: 28.JUL.2022 06:38:35

Figure 51 – NEUTRAL.
115 VAC 60 Hz.



12 Line Surge

Differential mode input line surge testing was completed on a single test unit to IEC61000-4-5. Input voltage was set at 115 VAC / 60 Hz. Output was loaded at full load (5V/50mA) using a 100 Ω fixed resistor and operation was verified following each surge event.

12.1 Differential Surge Test Results

Source Impedance: 2 Ω

Repetition Rate: 1/30 s

No. of surge strike per location: 10 strikes

DM Surge Level (V)	Input Voltage (VAC)	Injection Location	Injection Phase ($^{\circ}$)	Test Result (Pass/Fail)
+1000	115	L to N	0	Pass
-1000	115	L to N	0	Pass
+1000	115	L to N	90	Pass
-1000	115	L to N	90	Pass
+1000	115	L to N	180	Pass
-1000	115	L to N	180	Pass
+1000	115	L to N	270	Pass
-1000	115	L to N	270	Pass

Note: In all PASS results, no damage and no auto-restart was observed.

12.2 Ring Wave Surge Test Results

Source Impedance: 12 Ω

Repetition Rate: 1/30 s

No. of surge strike per location: 10 strikes

Surge Level (V)	Input Voltage (VAC)	Injection Location	Injection Phase ($^{\circ}$)	Test Result (Pass/Fail)
+2500	115	L to N	0	Pass
-2500	115	L to N	0	Pass
+2500	115	L to N	90	Pass
-2500	115	L to N	90	Pass
+2500	115	L to N	180	Pass
-2500	115	L to N	180	Pass
+2500	115	L to N	270	Pass
-2500	115	L to N	270	Pass

Note: In all PASS results, no damage and no auto-restart was observed.

13 Audible Noise

To reduce audible noise further, an off-the-shelf dog-bone or barrel type inductor is recommended. Horizontal mounting helps minimize PCB vibration that may amplify audible noise. DUT is encased in a dimming case to replicate real-life condition. The DUT was placed inside a sound isolated chamber fitted with a microphone for audible noise measurements. The microphone was placed approximately 10 cm on top of the DUT. Audible noise was tested at 115VAC at all load conditions.

13.1 Audible Noise Test Set-up

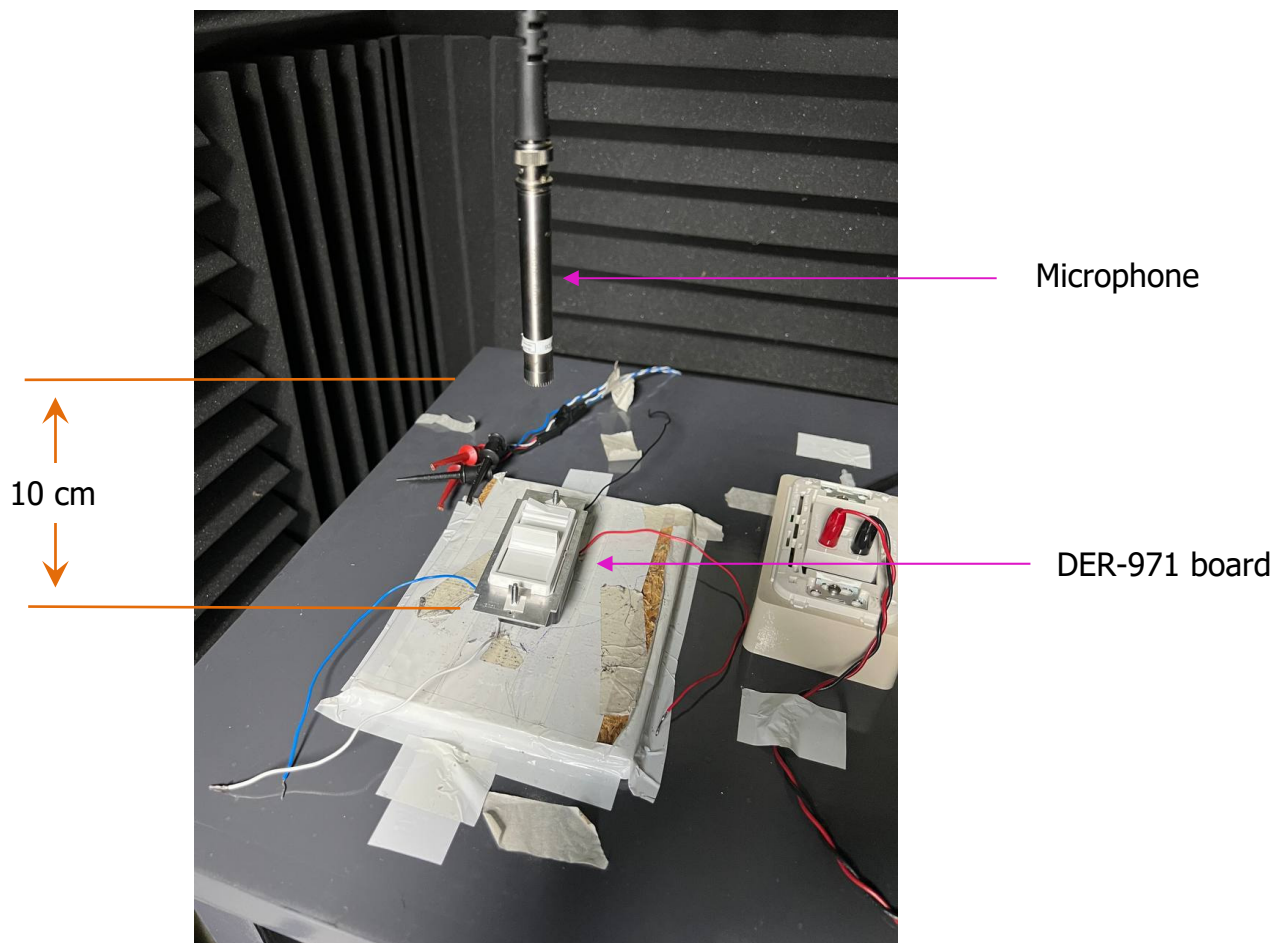


Figure 52 – Audible Noise Measurement Set-up Pictures.

13.2 Audible Noise Measurements

13.2.1 Audible Noise Scan

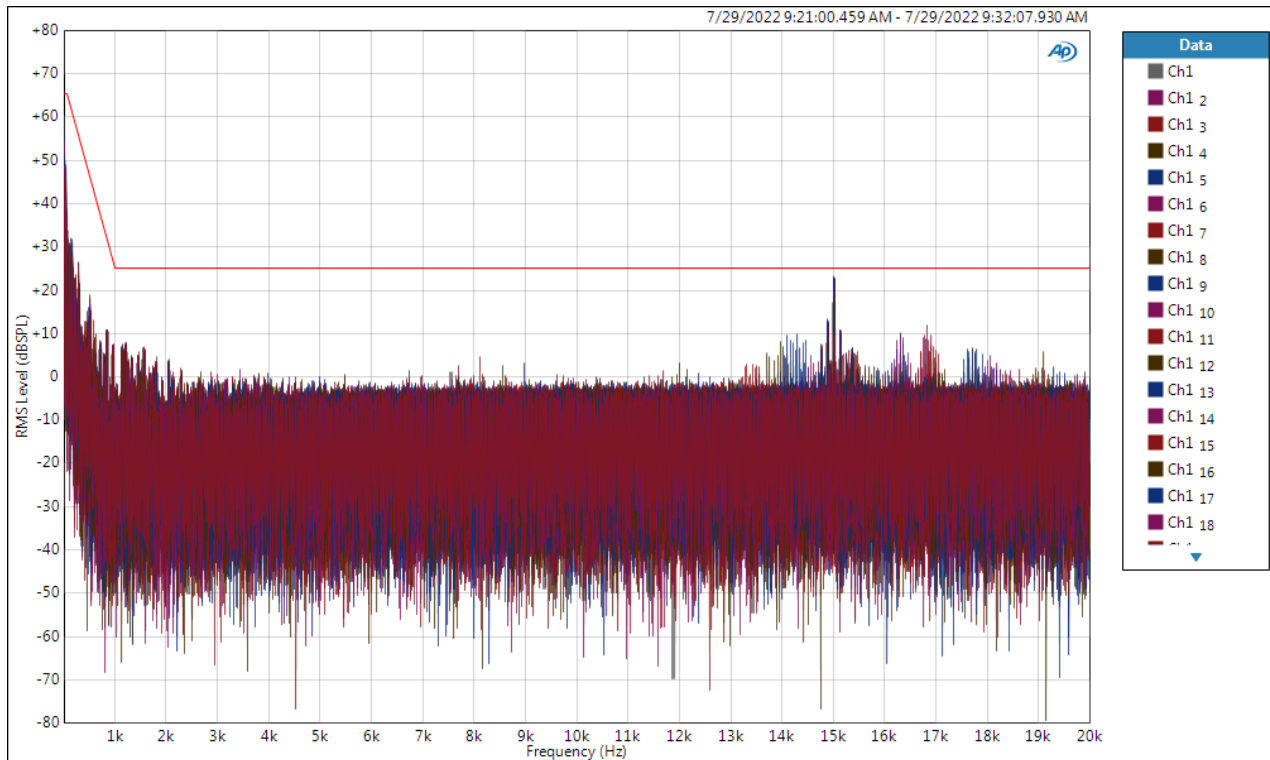


Figure 53 – Audible Noise Measurements at 115 VAC.

14 Revision History

Date	Author	Revision	Description and Changes	Reviewed
23-Jan-23	JEE	1.0	Initial Release.	Apps & Mktg



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Power Integrations Worldwide Sales Support Locations**WORLD HEADQUARTERS**

5245 Hellyer Avenue
San Jose, CA 95138, USA.
Main: +1-408-414-9200
Customer Service:
Worldwide: +1-65-635-64480
Americas: +1-408-414-9621
e-mail: usasales@power.com

CHINA (SHANGHAI)

Rm 2410, Charity Plaza, No. 88,
North Caoxi Road,
Shanghai, PRC 200030
Phone: +86-21-6354-6323
e-mail: chinasales@power.com

CHINA (SHENZHEN)

17/F, Hivac Building, No. 2, Keji
Nan 8th Road, Nanshan District,
Shenzhen, China, 518057
Phone: +86-755-8672-8689
e-mail: chinasales@power.com

GERMANY (AC-DC/LED Sales)

Einsteinring 24
85609 Dornach/Aschheim
Germany
Tel: +49-89-5527-39100
e-mail: eurosales@power.com

GERMANY (Gate Driver Sales)

HellwegForum 1
59469 Ense
Germany
Tel: +49-2938-64-39990
e-mail: igbt-driver.sales@power.com

INDIA

#1, 14th Main Road
Vasanthanagar
Bangalore-560052
India
Phone: +91-80-4113-8020
e-mail: indiasales@power.com

ITALY

Via Milanese 20, 3rd. Fl.
20099 Sesto San Giovanni (MI) Italy
Phone: +39-024-550-8701
e-mail: eurosales@power.com

JAPAN

Yusen Shin-Yokohama 1-chome Bldg.
1-7-9, Shin-Yokohama, Kohoku-ku
Yokohama-shi,
Kanagawa 222-0033 Japan
Phone: +81-45-471-1021
e-mail: japansales@power.com

KOREA

RM 602, 6FL
Korea City Air Terminal B/D,
159-6
Samsung-Dong, Kangnam-Gu,
Seoul, 135-728 Korea
Phone: +82-2-2016-6610
e-mail: koreasales@power.com

SINGAPORE

51 Newton Road,
#19-01/05 Goldhill Plaza
Singapore, 308900
Phone: +65-6358-2160
e-mail: singaporesales@power.com

TAIWAN

5F, No. 318, Nei Hu Rd.,
Sec. 1
Nei Hu District
Taipei 11493, Taiwan R.O.C.
Phone: +886-2-2659-4570
e-mail: taiwansales@power.com

UK

Building 5, Suite 21
The Westbrook Centre
Milton Road
Cambridge
CB4 1YG
Phone: +44 (0) 7823-557484
e-mail: eurosales@power.com

